MMSD4148T1

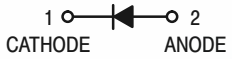
Switching Diode

Features

- SOD−123 Surface Mount Package
- High Breakdown Voltage
- Fast Speed Switching Time
- Available in 8 mm Tape and Reel
- Pb−Free Package is Available

ON Semiconductor®

http://onsemi.com



SOD−123
CASE 425
STYLE 1

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V_R	100	Vdc
Peak Forward Current	I_F	200	mAdc
Peak Forward Surge Current	$I_{FM(surge)}$	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board (Note 1) T_A = 25°C Derate above 25°C	P_D	425 3.4	mW mW/°C
Thermal Resistance Junction−to−Ambient	$R_{\theta JA}$	290	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR−5 = 1.0 oz Cu, 1.0 in^2 pad

DEVICE MARKING

51 = Specific Device Code
d = Date Code

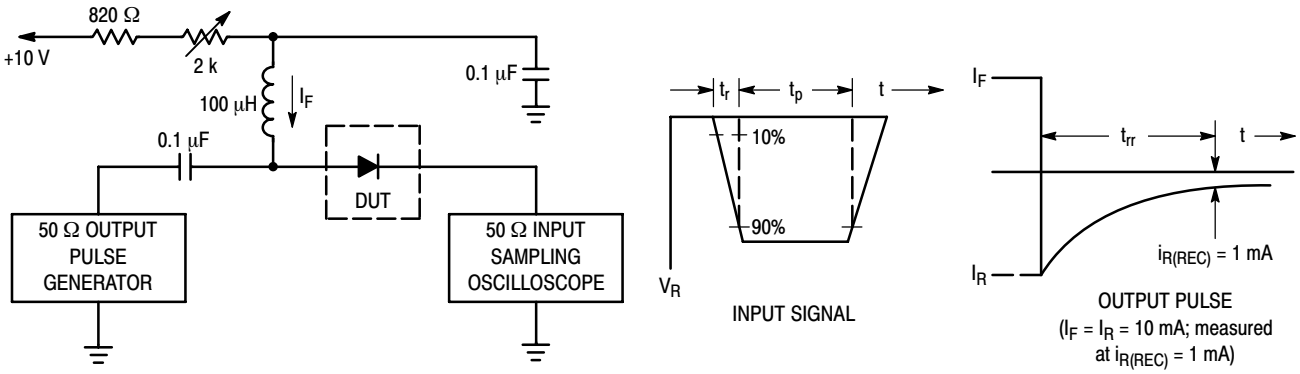
ORDERING INFORMATION

Device	Package	Shipping†
MMSD4148T1	SOD−123	3000 / Tape & Reel
MMSD4148T1G	SOD−123 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Breakdown Voltage (I_{BR} = 100 μAdc)	$V_{(BR)}$	100	–	Vdc
Reverse Voltage Leakage Current (V_R = 20 Vdc) (V_R = 75 Vdc)	I_R	– –	25 5.0	nAdc μAdc
Forward Voltage (I_F = 10 mAdc)	V_F	–	1000	mVdc
Diode Capacitance (V_R = 0 Vdc, f = 1.0 MHz)	C_D	–	4.0	pF
Reverse Recovery Time (I_F = I_R = 10 mAdc) (Figure 1)	t_{rr}	–	4.0	ns



1. A 2.0 kΩ variable resistor adjusted for a Forward Current (I_F) of 10 mA.
2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

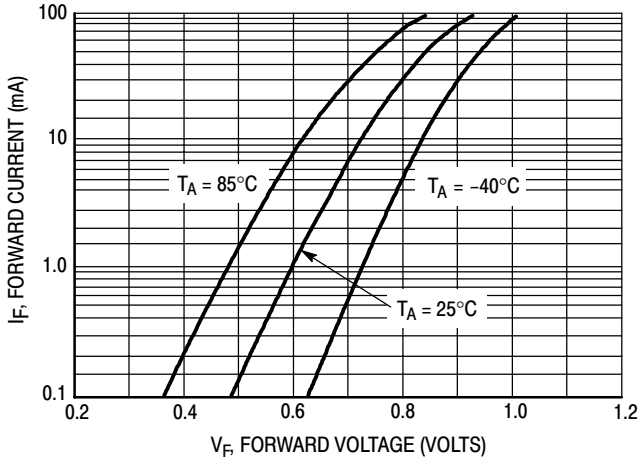


Figure 2. Forward Voltage

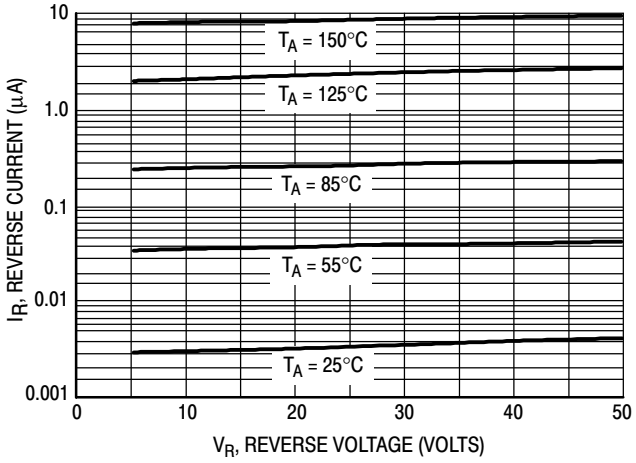


Figure 3. Leakage Current

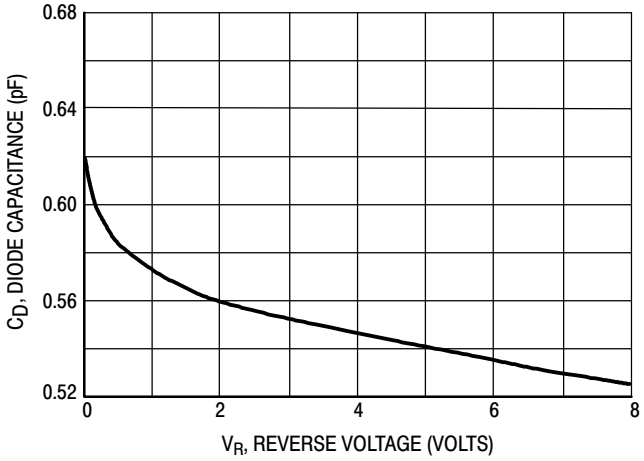
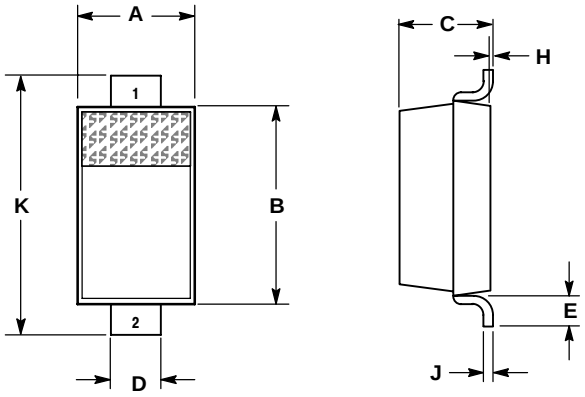


Figure 4. Capacitance

MMSD4148T1

PACKAGE DIMENSIONS

SOD−123
PLASTIC PACKAGE
CASE 425−04
ISSUE C

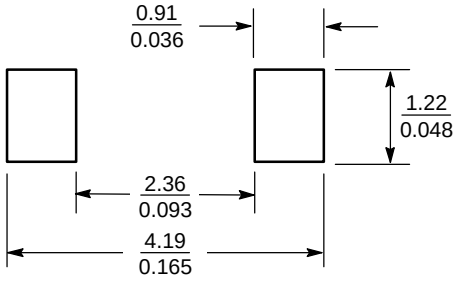


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.055	0.071	1.40	1.80
B	0.100	0.112	2.55	2.85
C	0.037	0.053	0.95	1.35
D	0.020	0.028	0.50	0.70
E	0.004	---	0.25	---
H	0.000	0.004	0.00	0.10
J	---	0.006	---	0.15
K	0.140	0.152	3.55	3.85

STYLE 1:
PIN 1. CATHODE
2. ANODE

SOLDERING FOOTPRINT*



SCALE 10:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

SOD−123

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
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